

Photomask Japan 2018 Oral Presentation

as of April 16

Date	Session Time	Sesion No.	Session Title	Program No.	Presentation Title	Name	Affiliation
April 18	10:10 - 10:40		Keynote Lecture	-	Evolutional Memory Technology	Nahomi Aoto	Micron Memory Japan
	10:40 - 12:10	1	NIL	1-1 (Invited)	Characterization and application of vertical material contrast generated by VUV exposure: making smooth 3D polymer micro-optics	Robert Kirchner	Technical University of Dresden
				1-2	Progress in Nanoimprint Wafer and Mask Systems for High Volume Semiconductor Manufacturing	Naaki Murasato	CANON INC.
				1-3	Fluorinated Polymer (FROMPTM) For Use in Nanoimprint Lithography	Hisanori Ohkita	Mitsui Chemicals, Inc.
				1-4	Improved Particle Control for High Volume Semiconductor Manufacturing for Nanoimprint Lithography	Tsuyoshi Arai	Canon Inc.
	13:20 - 14:40	2	FPD Photomasks	2-1	Enabling a common registration standard in the display industry	Peter Henriksson	Mycronic AB
				2-2	Shin-Etsu's advanced technology of planarization and shape controlling in FPD photomask substrates	Youkou Ishitsuka	Shin-Etsu Chemical Co.,Ltd.
				2-3	Nikon's FPD Photomask Blanks for Production of High Resolution Panels	Takashi Yagami	Nikon Corporation
				2-4	New Half-Tone Lithography Uses for FPD Proximity Printing	Shuheji Kobayashi	HOYA Corporation
	15:00 - 15:50	3	Writing & Metrology	3-1 (Invited)	Update on Multi-Beam Writing	Mathias Tomandl	IMS
				3-2	Multi-beam mask writer MBM-1000	Hiroshi Matsumoto	NuFlare Technology, Inc.
	15:50 - 16:30	4	Process & Repair	4-1	Dry etching technologies for Cr film	Takashi Miyamoto	SHIBAURA MECHATRONICS Corporation
				4-2	Update on the performance of photomask repair and clean with DUV femtosecond laser processes	Tod Robinson	RAVE LLC
	16:50 - 18:00	5	EDA & Lithography	5-1 (Invited)	Novel 3-Dimensional Photo Lithography Using Built-In Lens Mask	Yoshihiko Hirai	Osaka Prefecture University
				5-2	Demonstration of an effective Mask Proximity Correction for advanced photomask	Patrick Schiavone	Aselta Nanographics
5-3				Novel Thermoplastic SOC Materials for Planarization Use in Multilayer Lithography Process	Keisuke Kawashima	Mitsui Chemicals, Inc	
April 19	9:00 - 10:30	6	EUV masks (I)	6-1 (Invited)	eBeam Initiative Surveys Report Greatly Increased Confidence in EUV and Mask Process Correction Requirements	Aki Fujimura	eBeam Initiative
				6-2	Minimizing "Tone Reversal" during 19x nm Mask Inspection	Kazunori Seki	TOPPAN PRINTING CO., LTD.
				6-3	EUV Capping layer integrity	Pavel Nesladek	AMTC Dresden
				6-4	Fabrication of Ta based absorber EUV mask with SRAF	Keiko Morishita	Toshiba Memory Corporation
	10:50 - 11:50	7	EUV source for inspection	7-1	Droplet-based LPP Light Source for Actinic Patterned Mask Inspection for High Volume Manufacturing	Markus Brandstaetter	ETH Zurich, Laboratory for Energy Conversion
				7-2	Impact of droplet properties and Nd:YAG laser characteristics on the angular distribution of EUV radiation of a LPP EUV light source for HVM EUV Mask and Blank inspection	Marco Max Weber	LEC at ETH Zurich Switzerland
				7-3	EUV light source based on LPP for HVM mask inspection applications	Samir Shakir Ellwi	ISTEQ B.V.
	13:20 - 15:00	8	25th anniversary special session	8-1 (Invited)	"Mask Technology", the key of Moore's Law Scaling	Shinji Okazaki	ALITECS Corporation
				8-2 (Invited)	History of VSB Mask Writer and Future of Multi-beam Mask Writer	Noriaki Nakayamada	NFT
				8-3 (Invited)	Greeting Message for PMJ 25th Anniversary from EMLC	Uwe Behringer	EMLC Conference Chair
				8-4 (Invited)	Greetings Message for PMJ 25th Anniversary from BACUS	Jim Wiley	ASML President
	April 20	9:00 - 10:40	10	EUV Masks (II)	10-1 (Invited)	BACUS Best(TBD)	(TBD)
10-2 (Invited)					Progress on Actinic Blank Inspection tool and application to EUV mask observation	Hiroki Miyai	Lasertec
10-3					Blank defect coverage budget for 16nm half-pitch single EUV exposure	Rik Jonckheere	imec
10-4					Damage-free cleaning of EUV substrate for sub 10 nm half-pitch	Abbas Rastegar	Applied Materials
11:00 - 12:10		11	EUV masks (III)	11-1 (Invited)	AIMSTM EUV Platform: Going Beyond Actinic Review of EUV Photomasks	Martin Dietzel	Carl Zeiss
				11-2	Development of Transparent Backside Film for EUV Blanks	Yohei Ikebe	HOYA Corporation
				11-3	Advantages of EUV Blank Multi-Layers Deposited Using Advanced Physical Vapor Deposition Techniques	Vibhu Jindal	Applied Materials
13:40 - 15:20		12	EUV masks (IV)	12-1 (Invited)	HVM EUV Lithography: Managing without Actinic Patterned Mask Inspection: A Review of 2017 PMJ Panel	Jed Rankin	GlobalFoundries Inc.
				12-2 (Invited)	NXE pellicle Industry Update	Derk Brouns	ASML
				12-3	Development of closed-type EUV pellicle	Yosuke Ono	Mitsui Chemicals Inc.
				12-4	EUV Pellicle Metrology for High Volume Manufacturing	Rupert c c Perera	EUV Tech Inc.
				12-5	Qualification test on EUV photomask with EBL2 →Withdrawn	Herman Bekman	TNO